

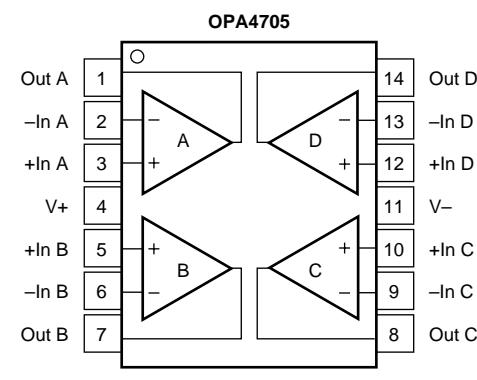
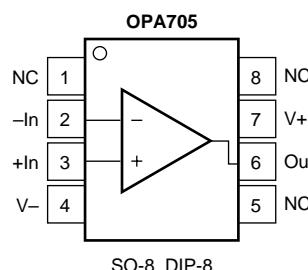
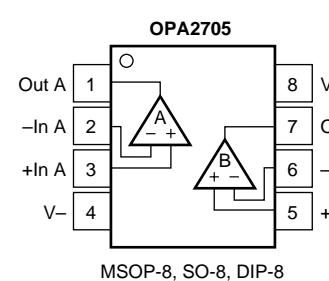
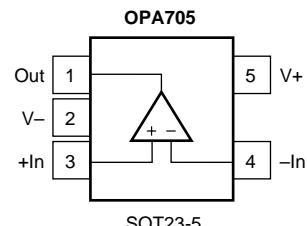
Low-Cost, CMOS, Rail-to-Rail, I/O OPERATIONAL AMPLIFIERS

FEATURES

- RAIL-TO-RAIL INPUT AND OUTPUT
- WIDE SUPPLY RANGE:
 - Single Supply: 4V to 12V
 - Dual Supplies: ± 2 to ± 6
- LOW QUIESCENT CURRENT: 160 μ A
- LIMITED RANGE CMRR: 96dB
- LOW OFFSET: 0.5mV
- HIGH SPEED: 1MHz, 0.6V/ μ s
- MicroSIZE PACKAGES:
 - SOT23-5, MSOP-8, TSSOP-14
- LOW INPUT BIAS CURRENT: 1pA

APPLICATIONS

- AUTOMOTIVE APPLICATIONS:
 - Audio, Sensor Applications, Security Systems
- PORTABLE EQUIPMENT
- ACTIVE FILTERS
- TRANSDUCER AMPLIFIER
- TEST EQUIPMENT
- DATA ACQUISITION



DESCRIPTION

The OPA705 series low-cost op amps are optimized for applications requiring rail-to-rail input and output swing. Single, dual, and quad versions are offered in a variety of packages. While the quiescent current is less than 200 μ A per amplifier, the OPA705 still offers excellent dynamic performance (1MHz GBW and 0.6V/ μ s SR) and unity-gain stability.

The OPA705 series is fully specified and guaranteed over the supply range of ± 2 V to ± 6 V. Input swing extends 300mV beyond the rail and the output swings to within 40mV of the rail.

The single version (OPA705) is available in the MicroSIZE SOT23-5 and in the standard SO-8 surface-mount packages. The dual version (OPA2705) is available in the MSOP-8, SO-8, and DIP-8 packages. The quad OPA4705 is available in the TSSOP-14 and SO-14 packages. All are specified for operation from -40°C to $+85^{\circ}\text{C}$.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Supply Voltage, V+ to V-	13.2V
Signal Input Terminals, Voltage ⁽²⁾	(V-) -0.3V to (V+) +0.3V
Current ⁽²⁾	10mA
Output Short-Circuit ⁽³⁾	Continuous
Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C

NOTES: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. (2) Input terminals are diode-clamped to the power supply rails. Input signals that can swing more than 0.3V beyond the supply rails should be current-limited to 10mA or less. (3) Short-circuit to ground, one amplifier per package.



ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

PRODUCT	DESCRIPTION	MINIMUM RECOMMENDED GAIN	PACKAGE	PACKAGE DRAWING NUMBER	PACKAGE MARKING	ORDERING NUMBER ⁽¹⁾	TRANSPORT MEDIA
OPA705NA "	Single, GBW = 1MHz	1 "	SOT23-5 "	331 "	A05 "	OPA705NA/250	Tape and Reel
OPA705UA "	Single, GBW = 1MHz	1 "	SO-8 "	182 "	OPA705UA "	OPA705NA/3K	Tape and Reel
OPA705PA	Single, GBW = 1MHz	1	DIP-8	006	OPA705PA	OPA705UA	Rails
OPA2705EA "	Dual, GBW = 1MHz	1 "	MSOP-8 "	337 "	B05 "	OPA2705EA/250	Tape and Reel
OPA2705UA "	Dual, GBW = 1MHz	1 "	SO-8 "	182 "	OPA2705UA "	OPA2705EA/2K5	Tape and Reel
OPA2705PA	Dual, GBW = 1MHz	1	DIP-8	006	OPA2705PA	OPA2705UA	Rails
OPA4705EA "	Quad, GBW = 1MHz	1 "	TSSOP-14 "	357 "	OPA4705EA "	OPA4705EA/250	Tape and Reel
OPA4705UA "	Quad, GBW = 1MHz	1 "	SO-14 "	235 "	OPA4705UA "	OPA4705EA/2K5	Tape and Reel
						OPA4705UA	Rails
						OPA4705UA/2K5	Tape and Reel

NOTE: (1) Models with a slash (/) are available only in Tape and Reel in the quantities indicated (e.g., /3K indicates 3000 devices per reel). Ordering 3000 pieces of "OPA705NA/3K" will get a single 3000-piece Tape and Reel.

ELECTRICAL CHARACTERISTICS: $V_S = 4V$ to $12V$

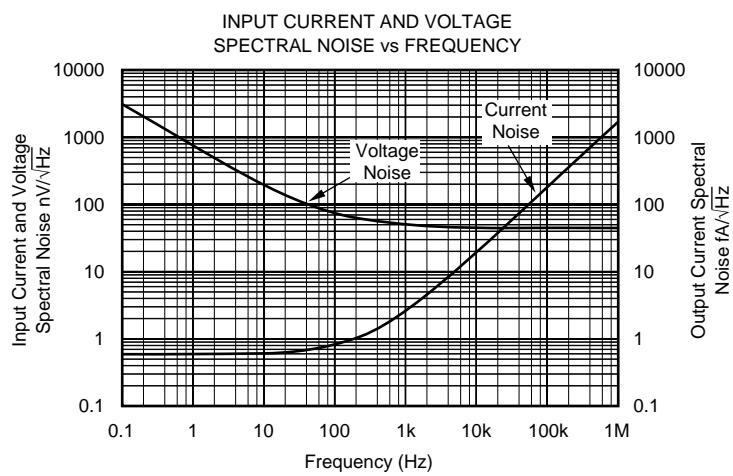
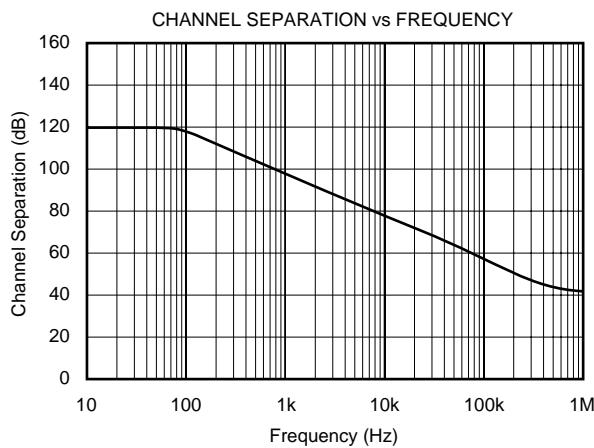
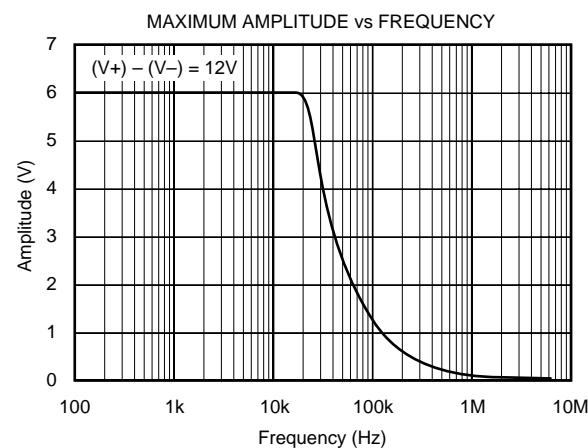
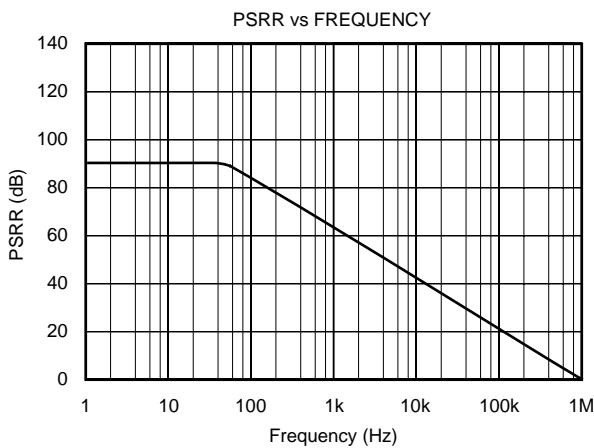
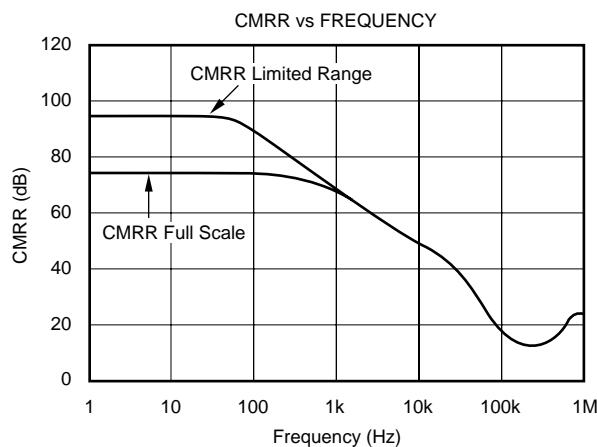
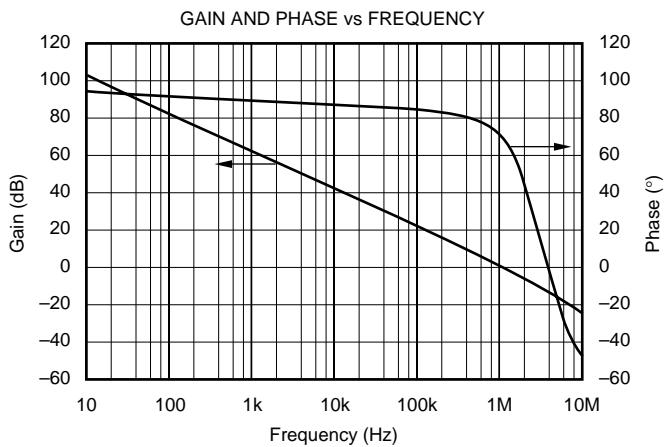
Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+85^{\circ}C$

At $T_A = +25^{\circ}C$, $R_L = 20k\Omega$ connected to $V_S/2$ and $V_{OUT} = V_S/2$, unless otherwise noted.

PARAMETER	CONDITION	OPA705NA, UA, PA OPA2705EA, UA, PA OPA4705EA, UA			UNITS
		MIN	TYP	MAX	
OFFSET VOLTAGE					
Input Offset Voltage	V_{OS}	± 0.5	± 5	± 5	mV
Drift	dV_{OS}/dT	± 4	± 4	± 4	$\mu V/C$
vs Power Supply	$PSRR$	20	20	100	$\mu V/V$
Over Temperature		100	1	98	$\mu V/V$
Channel Separation, dc $f = 1kHz$		$R_L = 20k\Omega$			$\mu V/V$
					dB
INPUT VOLTAGE RANGE					
Common-Mode Voltage Range	V_{CM}	$(V-) - 0.3$	$(V+) + 0.3$	$(V-) - 0.3$	V
Common-Mode Rejection Ratio over Temperature	$CMRR$	66	77	74	dB
		$V_S = \pm 5V, (V-) < V_{CM} < (V+) - 0.3V$			dB
		$V_S = \pm 5V, (V-) < V_{CM} < (V+)$			dB
over Temperature		66	96	93	dB
		$V_S = \pm 5V, (V-) - 0.3V < V_{CM} < (V+) - 2V$			dB
		$V_S = \pm 5V, (V-) < V_{CM} < (V+) - 2V$			dB
INPUT BIAS CURRENT					
Input Bias Current	I_B	$V_S = \pm 5V, V_{CM} = 0V$	± 1	± 10	pA
Input Offset Current	I_{OS}	$V_S = \pm 5V, V_{CM} = 0V$	± 0.5	± 10	pA
INPUT IMPEDANCE					
Differential			$4 \cdot 10^9 \parallel 4$		$\Omega \parallel pF$
Common-Mode			$5 \cdot 10^{12} \parallel 4$		$\Omega \parallel pF$
NOISE					
Input Voltage Noise, $f = 0.1Hz$ to $10Hz$	e_n	$V_S = \pm 5V, V_{CM} = 0V$	6		μV_{p-p}
Input Voltage Noise Density, $f = 1kHz$		$V_S = \pm 5V, V_{CM} = 0V$	45		nV/\sqrt{Hz}
Current Noise Density, $f = 1kHz$	i_n	$V_S = \pm 5V, V_{CM} = 0V$	2.5		fA/\sqrt{Hz}
OPEN-LOOP GAIN					
Open-Loop Voltage Gain	A_{OL}	$R_L = 100k\Omega, (V-) + 0.1V < V_O < (V+) - 0.1V$	120		dB
		$R_L = 20k\Omega, (V-) + 0.075V < V_O < (V+) - 0.075V$	110		dB
over Temperature		$R_L = 20k\Omega, (V-) + 0.075V < V_O < (V+) - 0.075V$	106		dB
		$R_L = 5k\Omega, (V-) + 0.15V < V_O < (V+) - 0.15V$	110		dB
over Temperature		$R_L = 5k\Omega, (V-) + 0.15V < V_O < (V+) - 0.15V$	106		dB
OUTPUT					
Voltage Output Swing from Rail		$R_L = 100k\Omega, A_{OL} > 80dB$	40		mV
		$R_L = 20k\Omega, A_{OL} > 100dB$	75		mV
		$R_L = 5k\Omega, A_{OL} > 100dB$	150		mV
Output Current	I_{OUT}	$ V_S - V_{OUT} < 1V$			mA
Short-Circuit Current	I_{SC}		± 10		mA
Capacitive Load Drive	C_{LOAD}		± 40		mA
			See Typical Performance Curves		
FREQUENCY RESPONSE					
Gain-Bandwidth Product	GBW	$C_L = 100pF$	1		MHz
Slew Rate	SR	$G = +1$	0.6		$V/\mu s$
Settling Time, 0.1%	t_S	$V_S = \pm 5V, G = +1$	15		μs
0.01%		$V_S = \pm 5V, 5V \text{ Step}, G = +1$	20		μs
Overload Recovery Time		$V_S = \pm 5V, 5V \text{ Step}, G = +1$	3		μs
Total Harmonic Distortion + Noise	$THD+N$	$V_{IN} \cdot \text{Gain} = V_S$	0.02		%
		$V_S = \pm 5V, V_O = 3V_{p-p}, G = +1, f = 1kHz$			
POWER SUPPLY					
Specified Voltage Range, Single Supply	V_S		4		V
Specified Voltage Range, Dual Supplies	V_S		± 2		V
Operating Voltage Range			3.6 to 12		V
Quiescent Current (per amplifier)	I_Q	$I_O = 0$	160	250	μA
over Temperature			200		μA
			150		μA
			100		μA
			100		μA
TEMPERATURE RANGE					
Specified Range			-40	85	$^{\circ}C$
Operating Range			-55	125	$^{\circ}C$
Storage Range			-65	150	$^{\circ}C$
Thermal Resistance	θ_{JA}				$^{\circ}C/W$
SOT23-5 Surface-Mount			200		$^{\circ}C/W$
MSOP-8 Surface-Mount			150		$^{\circ}C/W$
TSSOP-14 Surface-Mount			100		$^{\circ}C/W$
SO-8 Surface Mount			150		$^{\circ}C/W$
SO-14 Surface Mount			100		$^{\circ}C/W$
DIP-8			100		$^{\circ}C/W$

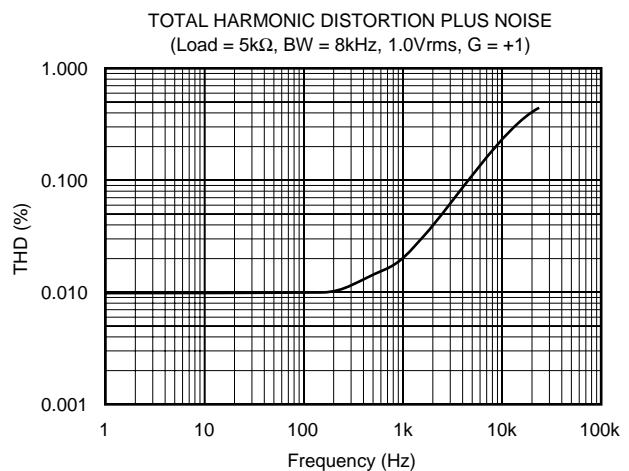
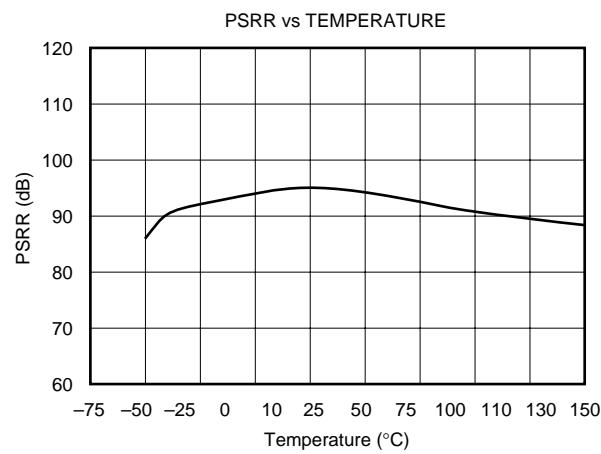
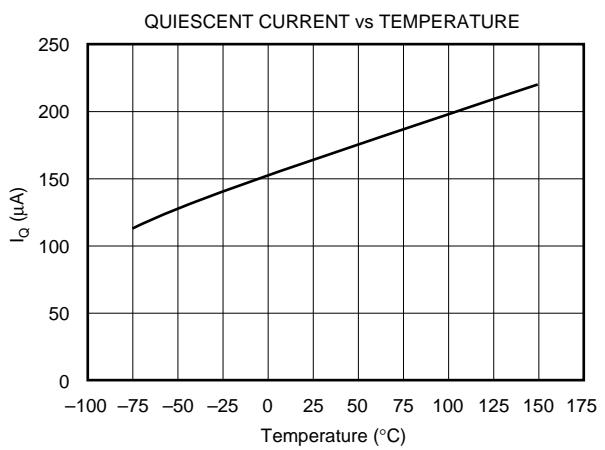
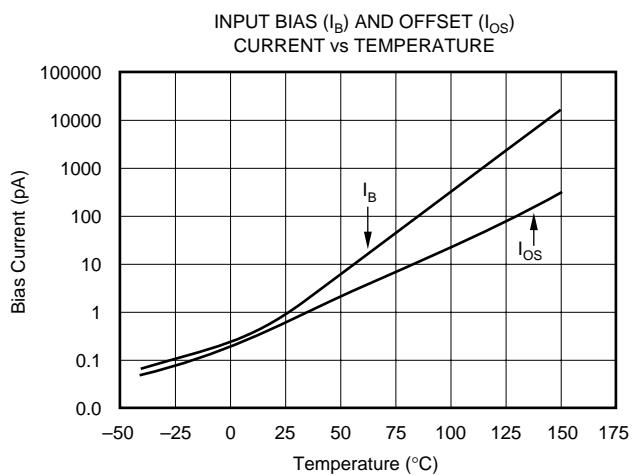
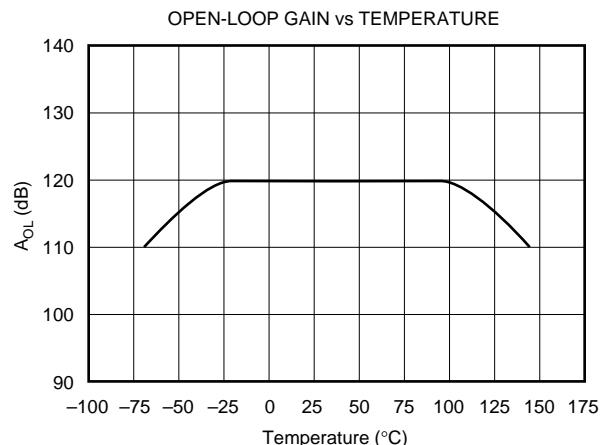
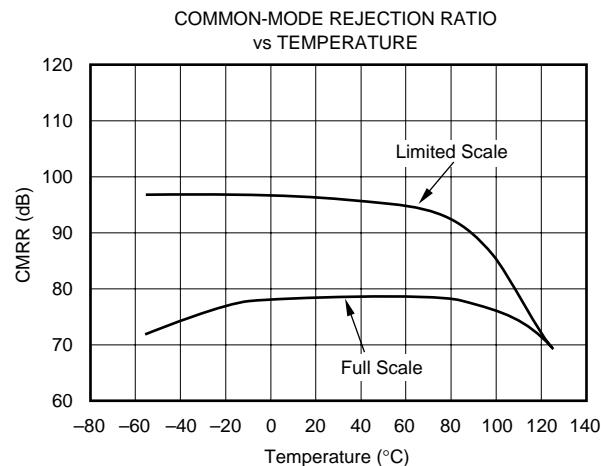
TYPICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_S = \pm 5\text{V}$, and $R_L = 20\text{k}\Omega$, unless otherwise noted.



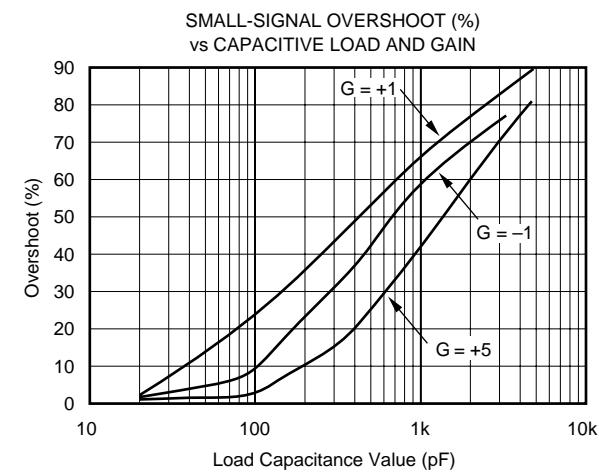
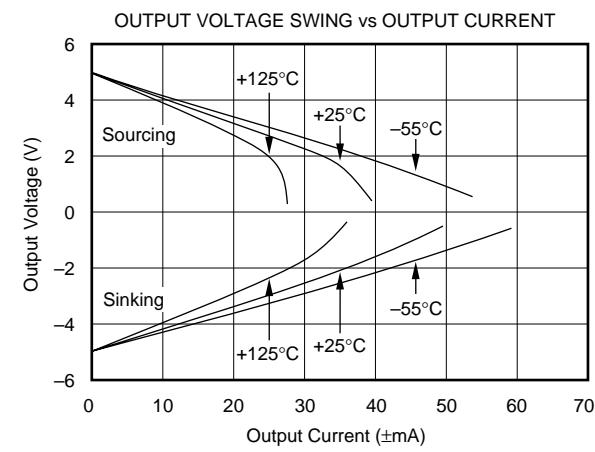
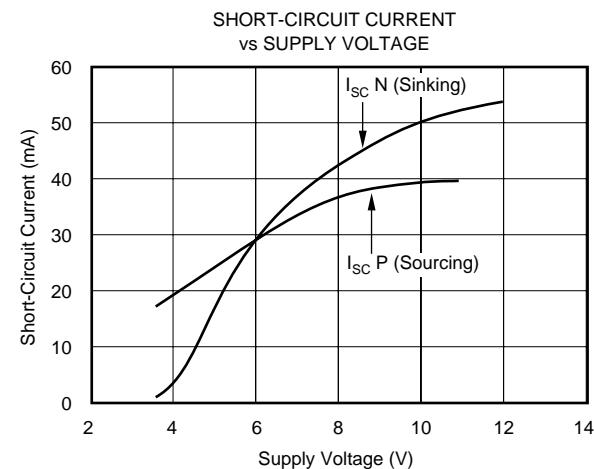
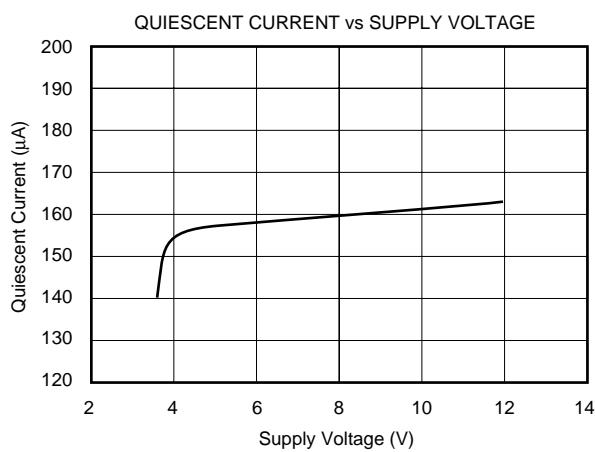
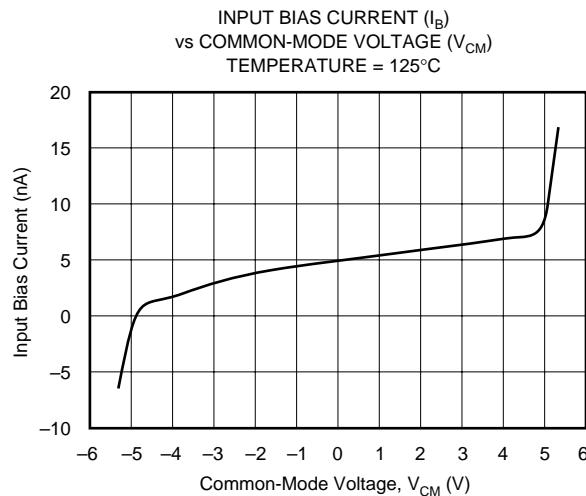
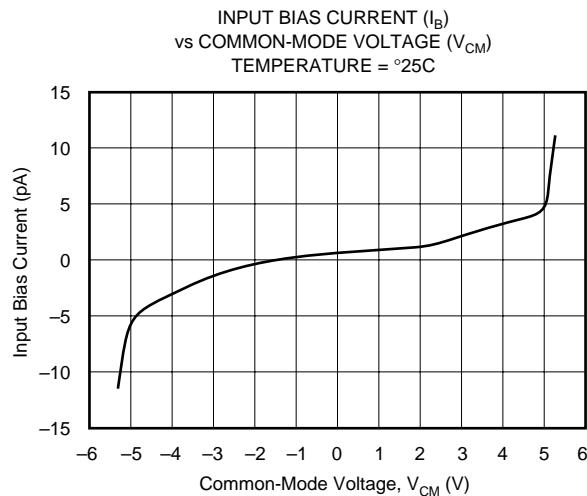
TYPICAL CHARACTERISTICS (Cont.)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 5\text{V}$, and $R_L = 20\text{k}\Omega$, unless otherwise noted.



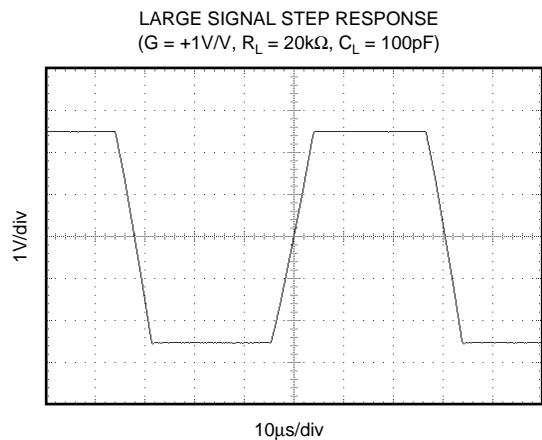
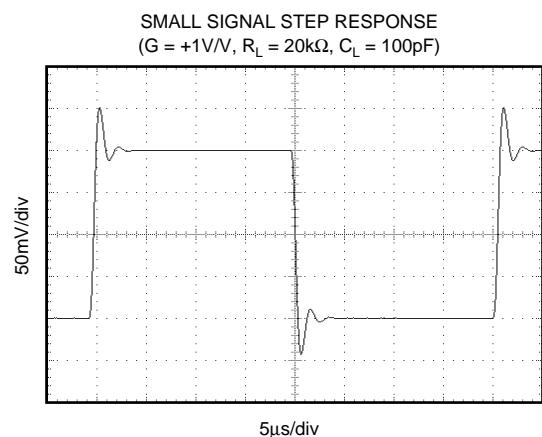
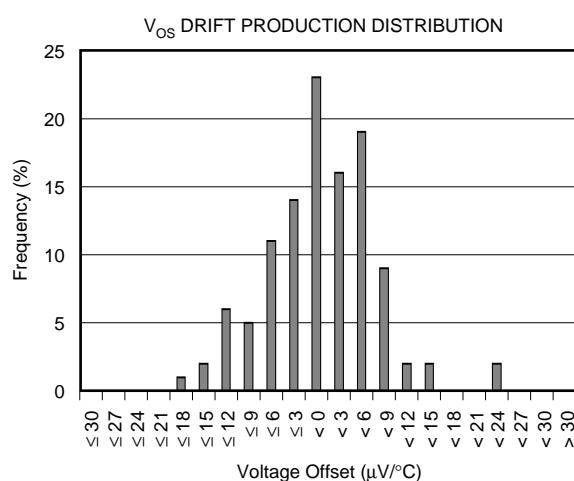
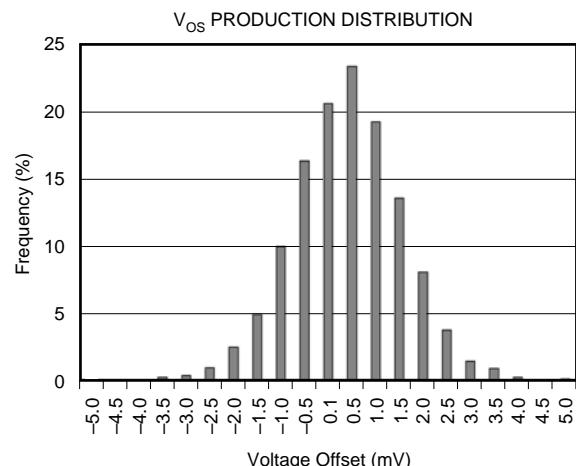
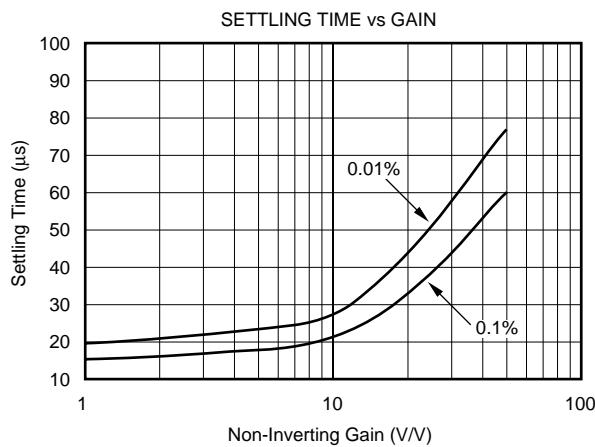
TYPICAL CHARACTERISTICS (Cont.)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 5\text{V}$, and $R_L = 20\text{k}\Omega$, unless otherwise noted.



TYPICAL CHARACTERISTICS (Cont.)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 5\text{V}$, and $R_L = 20\text{k}\Omega$, unless otherwise noted.



APPLICATIONS INFORMATION

OPA705 series op amps can operate on 160 μ A quiescent current from a single (or split) supply in the range of 4V to 12V ($\pm 2V$ to $\pm 6V$), making them highly versatile and easy to use. The OPA705 is unity-gain stable and offers 1MHz bandwidth and 0.6V/ μ s slew rate.

Rail-to-rail input and output swing helps maintain dynamic range, especially in low supply applications. Figure 1 shows the input and output waveforms for the OPA705 in unity-gain configuration. Operation is from a $\pm 5V$ supply with a 100k Ω load connected to $V_S/2$. The input is a 10Vp-p sinusoid. Output voltage is approximately 10Vp-p.

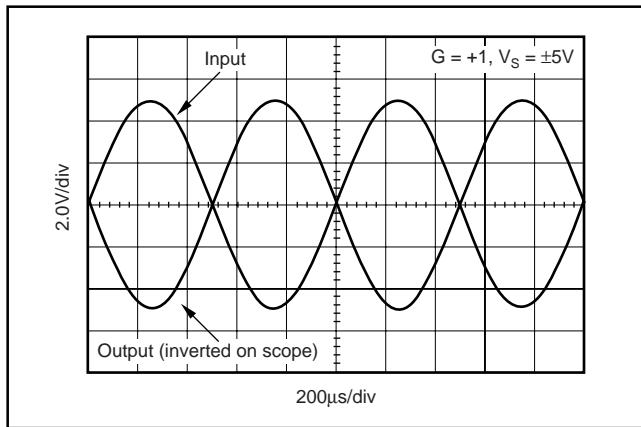


FIGURE 1. Rail-to-Rail Input and Output.

Power-supply pins should be bypassed with 1000pF ceramic capacitors in parallel with 1 μ F tantalum capacitors.

OPERATING VOLTAGE

OPA705 series op amps are fully specified and guaranteed from +4V to +12V over a temperature range of -40°C to +85°C. Parameters that vary significantly with operating voltages or temperature are shown in the Typical Characteristics.

RAIL-TO-RAIL INPUT

The input common-mode voltage range of the OPA705 series extends 300mV beyond the supply rails at room temperature. This is achieved with a complementary input stage—an N-channel input differential pair in parallel with a P-channel differential pair, as shown in Figure 2. The N-channel pair is active for input voltages close to the positive rail, typically $(V_+) - 2.0V$ to 300mV above the positive supply, while the P-channel pair is on for inputs from 300mV below the negative supply to approximately $(V_+) - 1.5V$. There is a small transition region, typically $(V_+) - 2.0V$ to $(V_+) - 1.5V$, in which both pairs are on. This 500mV transition region can vary $\pm 100mV$ with process variation. Thus, the transition region (both stages on) can range from $(V_+) - 2.1V$ to $(V_+) - 1.4V$ on the low end, up to $(V_+) - 1.9V$ to $(V_+) - 1.6V$ on the high end. Within the 500mV transition region PSRR, CMRR, offset voltage, and offset drift, and THD may vary compared to operation outside this region.

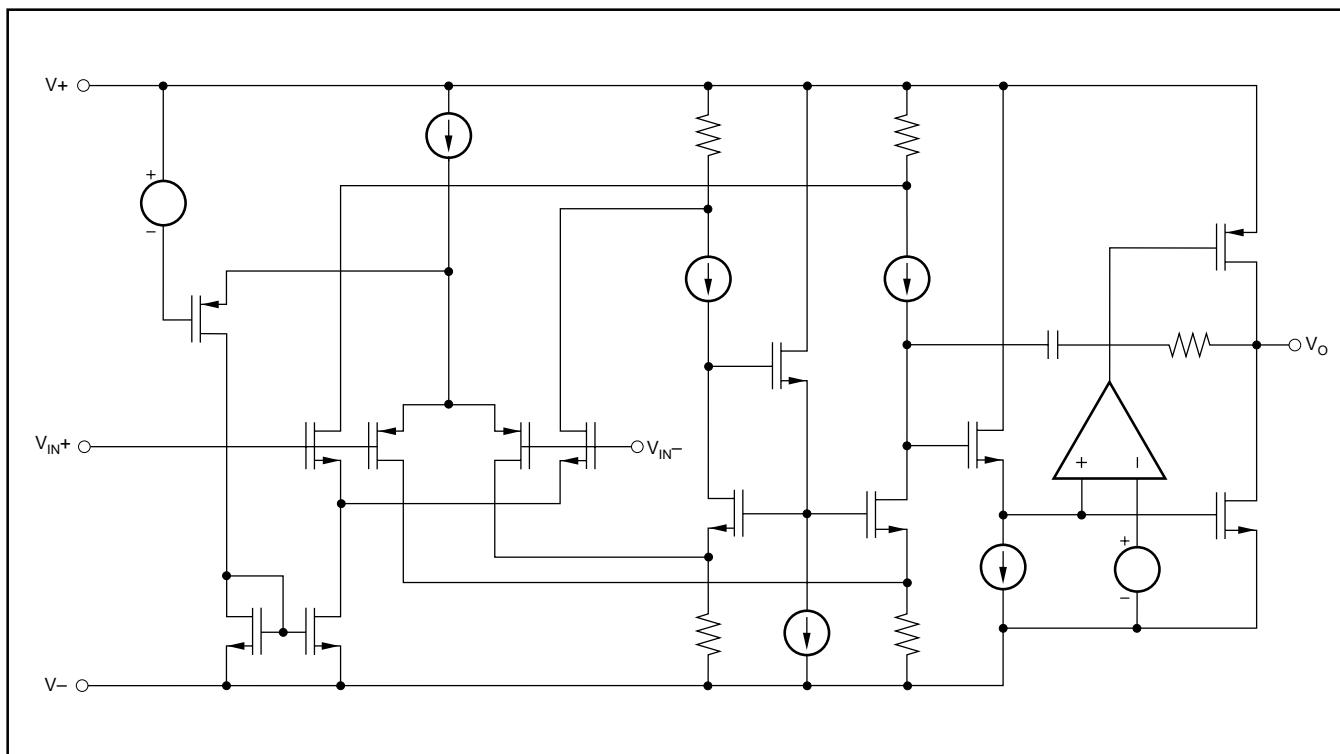


FIGURE 2. Simplified Schematic.

INPUT VOLTAGE

Device inputs are protected by ESD diodes that will conduct if the input voltages exceed the power supplies by more than approximately 300mV. Momentary voltages greater than 300mV beyond the power supply can be tolerated if the current is limited to 10mA. This is easily accomplished with an input resistor, as shown in Figure 3. Many input signals are inherently current-limited to less than 10mA; therefore, a limiting resistor is not always required. The OPA705 features no phase inversion when the inputs extend beyond supplies if the input current is limited, as seen in Figure 4.

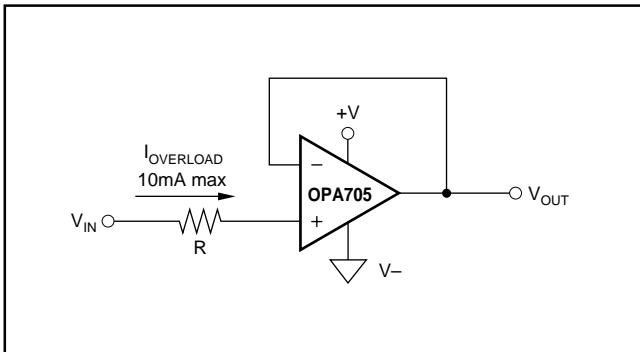


FIGURE 3. Input Current Protection for Voltages Exceeding the Supply Voltage.

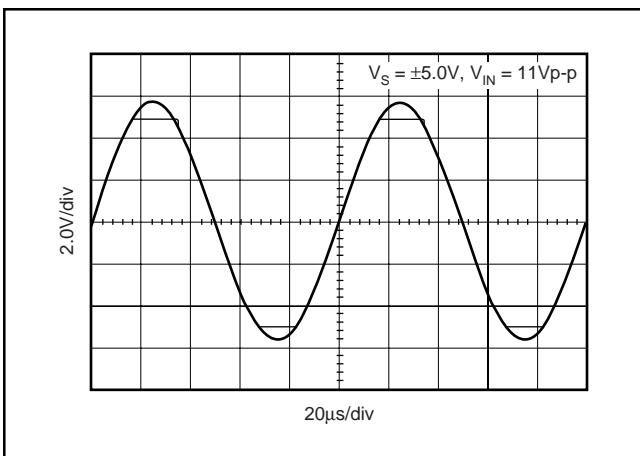


FIGURE 4. OPA705—No Phase Inversion with Inputs Greater than the Power-Supply Voltage.

RAIL-TO-RAIL OUTPUT

A class AB output stage with common-source transistors is used to achieve rail-to-rail output. This output stage is capable of driving $1\text{k}\Omega$ loads connected to any point between $\text{V}+$ and ground. For light resistive loads ($> 100\text{k}\Omega$), the output voltage can swing to 40mV from the supply rail. With moderate resistive loads ($20\text{k}\Omega$), the output can swing to within 75mV from the supply rails while maintaining high open-loop gain (see the typical performance curve “Output Voltage Swing vs Output Current”).

CAPACITIVE LOAD AND STABILITY

The OPA705 series op amps can drive up to 1000pF pure capacitive load. Increasing the gain enhances the amplifier’s ability to drive greater capacitive loads (see the typical performance curve “Small Signal Overshoot vs Capacitive Load”).

One method of improving capacitive load drive in the unity-gain configuration is to insert a 10Ω to 20Ω resistor inside the feedback loop, as shown in Figure 5. This reduces ringing with large capacitive loads while maintaining DC accuracy.

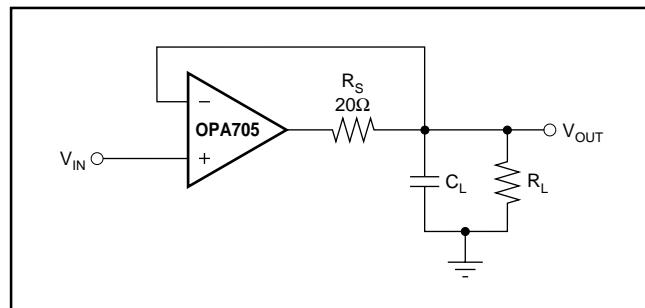


FIGURE 5. Series Resistor in Unity-Gain Buffer Configuration Improves Capacitive Load Drive.

APPLICATION CIRCUITS

The OPA705 series op amps are optimized for driving medium-speed sampling data converters. Figure 6 shows the OPA705 in a dual-supply buffered reference configuration for the DAC7644. The DAC7644 is a 16-bit, low-power, quad-voltage output converter. Small size makes the combination ideal for automatic test equipment, data acquisition systems, and other low-power space-limited applications.

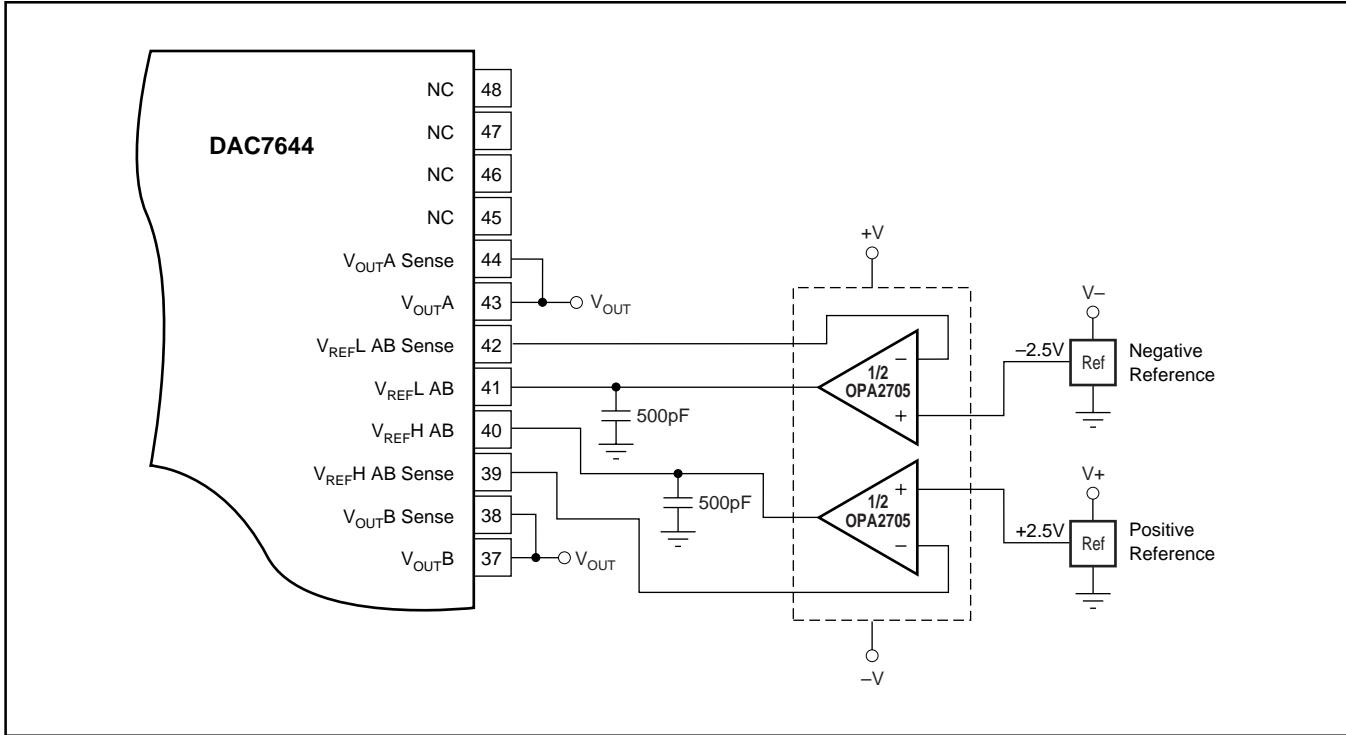


FIGURE 6. OPA705 as Dual Supply Configuration-Buffered References for the DAC7644.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
OPA2705EA/250	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	B05	Samples
OPA2705EA/250G4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	B05	Samples
OPA2705PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	OPA2705PA	Samples
OPA2705PAG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	OPA2705PA	Samples
OPA2705UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA2705UA	Samples
OPA2705UAG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA2705UA	Samples
OPA4705EA/250	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA4705EA	Samples
OPA4705EA/250G4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA4705EA	Samples
OPA4705EA/2K5	ACTIVE	TSSOP	PW	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA4705EA	Samples
OPA4705EA/2K5G4	ACTIVE	TSSOP	PW	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA4705EA	Samples
OPA4705UA	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA4705UA	Samples
OPA4705UAG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA4705UA	Samples
OPA705NA/250	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A05	Samples
OPA705NA/250G4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A05	Samples
OPA705NA/3K	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	A05	Samples
OPA705PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	OPA705PA	Samples
OPA705UA	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	OPA705UA	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

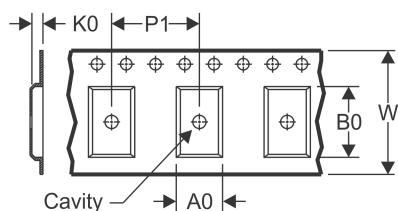
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

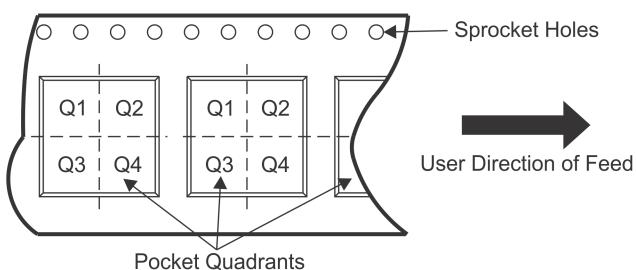
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION
REEL DIMENSIONS

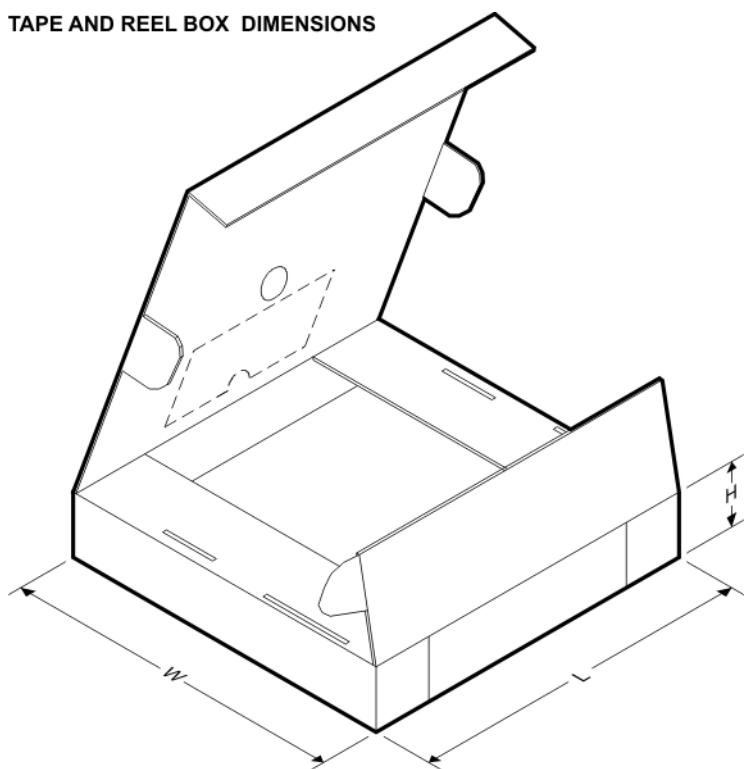
TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2705EA/250	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA4705EA/250	TSSOP	PW	14	250	180.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
OPA4705EA/2K5	TSSOP	PW	14	2500	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
OPA705NA/250	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
OPA705NA/3K	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2705EA/250	VSSOP	DGK	8	250	210.0	185.0	35.0
OPA4705EA/250	TSSOP	PW	14	250	210.0	185.0	35.0
OPA4705EA/2K5	TSSOP	PW	14	2500	367.0	367.0	35.0
OPA705NA/250	SOT-23	DBV	5	250	180.0	180.0	18.0
OPA705NA/3K	SOT-23	DBV	5	3000	180.0	180.0	18.0

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products	Applications
Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity
	TI E2E Community
	e2e.ti.com